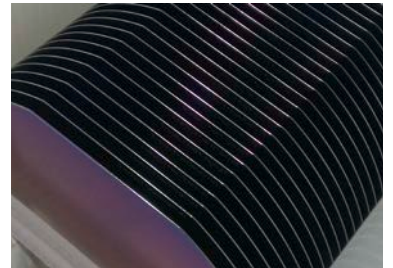
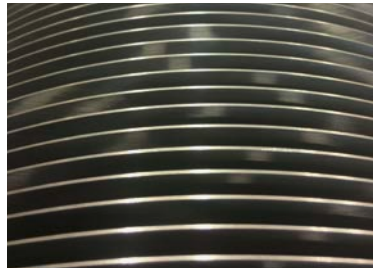
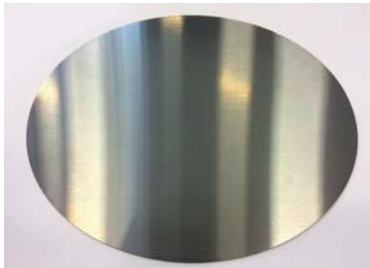


# DW 292

MULTI WIRE SAW



WORK PIECE DIMENSIONS:  
MAX. Ø 305 MM × 650 MM



## 12" WAFER AT HIGHEST PRECISION AND THROUGHPUT

- ✓ High wire speed and acceleration
- ✓ Patented Diamond Wire Management System (DWMS)
- ✓ High process automation
- ✓ Sophisticated work piece rocking

SMART SLICING TECHNOLOGY FOR SEMICONDUCTOR WAFERING

## HIGHLIGHTS DW 292

- ✔ Sophisticated work piece rocking for maximum precision
- ✔ High throughput:  
35 m/s wire speed,  
12 m/s<sup>2</sup> acceleration
- ✔ DWMS:  
60 µm wire capability
- ✔ Shortest wire path:  
Only <1.9 m on one side, easy wire set-up and constant tension
- ✔ Robust machine:  
Mineral cast, low temperature dependency, low vibration, low noise
- ✔ HMI: New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- ✔ Option: Automatic cutting fluid exchange
- ✔ Option: MES interface (SECS / GEM)



Long load length for high output



Optimized work piece rocking for higher wafer quality



Easy operation for higher yield

TECHNICAL DATA	DW 292 FEATURES
Web length [mm]	660
Max. work piece dimensions [mm]	Ø 305 × 650
Wire speed [m/sec]	35
Wire acceleration [m/s <sup>2</sup> ]	12 (<3.5 s)
Min. wire diameter [µm]	60
Max. wire tension [N]	28
Rocking principle	Rocking of work piece
Rocking angle [°]	± 8
Wire guide roller axis distance [mm]	580
Cutting fluid tank [l]	300
Machine dimensions [L × W × H] [mm]	3610 × 1380 × 2860
Machine weight [kg]	9300

**GET IN TOUCH WITH US TODAY**  
**TOGETHER WE WILL FIND A SOLUTION**  
**FOR YOUR REQUIREMENTS**

**PRECISION SURFACING SOLUTIONS GMBH**

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